## **Dotted box > PCB manufacturer info**

Layer Name	Туре	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric	core	FR4	59.44882 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0
	F.Silkscreen F.Paste F.Mask F.Cu Dielectric B.Cu B.Mask B.Paste	F.Mask Top Solder Mask F.Cu copper Dielectric core B.Cu copper B.Mask Bottom Solder Mask	F.Silkscreen Top Silk Screen Not specified F.Paste Top Solder Paste F.Mask Top Solder Mask Not specified F.Cu copper Dielectric core FR4 B.Cu copper B.Mask Bottom Solder Mask Not specified B.Paste Bottom Solder Paste	F.Silkscreen Top Silk Screen Not specified 0 mils F.Paste Top Solder Paste 0 mils F.Mask Top Solder Mask Not specified 0.3937 mils F.Cu copper 1.37795 mils B.Cu copper FR4 59.44882 mils B.Cu copper 1.37795 mils B.Mask Bottom Solder Mask Not specified 0.3937 mils B.Paste Bottom Solder Paste 0 mils	F.Silkscreen Top Silk Screen Not specified 0 mils Not specified F.Paste Top Solder Paste 0 mils F.Mask Top Solder Mask Not specified 0.3937 mils Not specified F.Cu copper 1.37795 mils Dielectric core FR4 59.44882 mils Not specified B.Cu copper 1.37795 mils Not specified B.Cu copper 0 1.37795 mils Not specified B.Paste Bottom Solder Mask Not specified 0.3937 mils Not specified B.Paste Bottom Solder Paste 0 mils	F.Silkscreen Top Silk Screen Not specified 0 mils Not specified 1 F.Paste Top Solder Paste 0 mils 1 F.Mask Top Solder Mask Not specified 0.3937 mils Not specified 3.3 F.Cu copper 1.37795 mils 1 Dielectric core FR4 59.44882 mils Not specified 4.5 B.Cu copper 1.37795 mils 1 B.Mask Bottom Solder Mask Not specified 0.3937 mils Not specified 3.3 B.Paste Bottom Solder Paste 0 mils 1

## BOARD CHARACTERISTICS

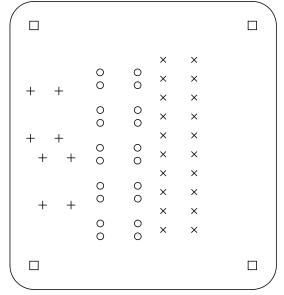
Copper Layer Count: 2 Board Thickness: 1.6000 mm

Board overall dimensions: 70.4850 mm x 76.2000 mm

Min track/spacing: 0.0000 mm / 0.0000 mm Min hole diameter: 0.3000 mm Copper Finish: None Impedance Control: No

Plated Board Edge: No Castellated pads:

Edge card connectors:



Drill Map: × 1.397mm / 0.0550" (20 holes) ○ 1.800mm / 0.0709" (20 holes) + 2.108mm / 0.0830" (8 holes) □ 3.175mm / 0.1250" (4 holes) (not plated) NOTES LAYERS 1.Layers: 2 2.Thickness: 1.6 3.Surface finish: HASL 4.Outer Copper Weight: 2oz 5.Via covering: Tented User.1 6.Min hole size: .3mm 7.Gold Fingers: No Edge.Cuts 8.Castellated Holes: No 9.Edge Plating: No



## Spartan Robotics

File: PowerDistribution.kicad\_pcb

Title: Power Distribution Board

Size: B Date: 2024-10-12 KiCad E.D.A. 8.0.5 Rev: R2 Page: 1/1